PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

CONVEYING PARTY DATA

Name	Execution Date
Hung-Ming Chen	09/01/2011
Chih-Hao Chang	09/01/2011
Chih-Hao Yu	09/01/2011

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	
Street Address:	No. 8, Li-Hsin Rd. 6	
Internal Address:	Science-Based Industrial Park	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code:	300-77	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13919459

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	2011-0631-D1 / 24061.2544		
NAME OF SUBMITTER:	Scott T. Jarratt		
Signature:	/Scott T. Jarratt/		

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Date:	06/17/2013
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PATENT REEL: 030626 FRAME: 0002

Docket No.: 2011-0631 / 24061.1882

Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

(1)	Hung-Ming Chen	of	2F, No. 13, Jinshan 23rd Street, East District Hsinchu City 300, Taiwan, R.O.C.
(2)	Chih-Hao Chang	of	10F, No. 128, Section 2, Sheng-Li 7th Street Chu-Bei City, Hsin-Chu, Taiwan, R.O.C.
(3)	Chih-Hao Yu	of	No. 34, Neighborhood 9, Lutian Village, Nanxi District

have invented certain improvements in

IMPROVED SILICIDE FORMATION AND ASSOCIATED DEVICES

for which we have filed and executed an application for Letters Patent of the United States of America on September 8, 2011, as U.S. Serial No. 13/227, 979 ; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

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AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:

Hung-Ming Chen

Residence Address:

2F, No. 13, Jinshan 23rd Street, East District

Hsinchu City 300, Taiwan, R.O.C.

Dated: Hung-Miny Chen

Inventor Signature

Inventor Name:

Chih-Hao Chang

Residence Address:

10F, No. 128, Section 2, Sheng-Li 7th Street

Chu-Bei City, Hsin-Chu, Taiwan, R.O.C.

Dated: V Chih-ldao Chi

V >0(1.09.0).
Inventor Signature

Inventor Name:

Chih-Hao Yu

Residence Address:

No. 34, Neighborhood 9, Lutian Village, Nanxi District

Tainan City 715, Taiwan, R.O.C.

Dated: V Chih-Han Yu

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Inventor Signature

RECORDED: 06/17/2013